

NP75P03YDG

MOS FIELD EFFECT TRANSISTOR

R07DS0020EJ0200 Rev.2.00 Mar 16, 2011

Description

The NP75P03YDG is P-channel MOS Field Effect Transistor designed for high current switching applications.

Features

- Low on-state resistance
 - $R_{DS(on)} = 6.2 \text{ m}\Omega$ MAX. ($V_{GS} = -10 \text{ V}$, $I_D = -37.5 \text{ A}$)
- Low C_{iss} : $C_{iss} = 3200 \text{ pF TYP.} (V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V})$
- Logic level drive type
- Designed for automotive application and AEC-Q101 qualified
- Small size package 8-pin HSON

Ordering Information

Part No.	LEAD PLATING	PACKING	Package
NP75P03YDG -E1-AY *1	Pure Sn (Tin)	Tape 2500 p/reel	8-pin HSON, Taping (E1 type)
NP75P03YDG -E2-AY *1			8-pin HSON, Taping (E2 type)

Note: *1. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings ($T_A = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V _{GS} = 0 V)	V_{DSS}	-30	V
Gate to Source Voltage (V _{DS} = 0 V)	V_{GSS}	∓20	V
Drain Current (DC) (T _C = 25°C)	I _{D(DC)}	∓75	А
Drain Current (pulse) *1	I _{D(pulse)}	∓225	А
Total Power Dissipation (T _C = 25°C)	P _{T1}	138	W
Total Power Dissipation (T _A = 25°C) *2	P _{T2}	1.0	W
Channel Temperature	T _{ch}	175	°C
Storage Temperature	T _{stg}	−55 to +175	°C
Single Avalanche Current *3	I _{AS}	27	А
Single Avalanche Energy *3	E _{AS}	73	mJ



<R>

Thermal Resistance

Channel to Case Thermal Resistance $R_{th(ch-C)}$ 1.09 °C/W Channel to Ambient Thermal Resistance *2 $R_{th(ch-A)}$ 150 °C/W

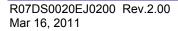
Notes: *1. $T_C = 25^{\circ}C$, $PW \le 10 \mu s$, Duty Cycle $\le 1\%$

*2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 0.8 mmt

*3. Starting T_{ch} = 25°C, V_{DD} = -15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = -20 \rightarrow 0 V

The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.





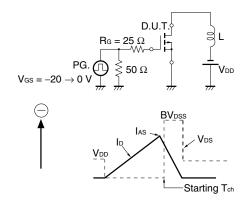
Electrical Characteristics ($T_A = 25^{\circ}C$)

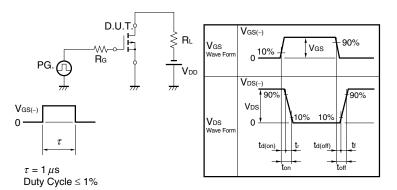
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I _{DSS}			-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$
Gate Leakage Current	I _{GSS}			∓100	nA	$V_{GS} = \mp 20 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Threshold Voltage	$V_{GS(th)}$	-1.0	-1.6	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$
Forward Transfer Admittance *1	y _{fs}	30	60		S	$V_{DS} = -5 \text{ V}, I_{D} = -37.5 \text{ A}$
Drain to Source On-state	R _{DS(on)1}		4.8	6.2	mΩ	$V_{GS} = -10 \text{ V}, I_D = -37.5 \text{ A}$
Resistance *1	R _{DS(on)2}		6.2	9.6	mΩ	$V_{GS} = -5 \text{ V}, I_D = -37.5 \text{ A}$
Input Capacitance	C _{iss}		3200	4800	pF	$V_{DS} = -25 \text{ V},$
Output Capacitance	Coss		660	990	pF	$V_{GS} = 0 V$,
Reverse Transfer Capacitance	C _{rss}		390	700	pF	f = 1 MHz
Turn-on Delay Time	t _{d(on)}		13	26	ns	$V_{DD} = -15 \text{ V}, I_D = -37.5 \text{ A},$
Rise Time	t _r		13	32	ns	$V_{GS} = -10 \text{ V},$
Turn-off Delay Time	t _{d(off)}		270	540	ns	$R_G = 0 \Omega$
Fall Time	t _f		180	440	ns	
Total Gate Charge	Q_{G}		94	141	nC	V _{DD} = -24 V,
Gate to Source Charge	Q_{GS}		18		nC	$V_{GS} = -10 \text{ V},$
Gate to Drain Charge	Q_{GD}		29		nC	I _D = -75 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$		1.0	1.5	V	$I_F = -75 \text{ A}, V_{GS} = 0 \text{ V}$
Reverse Recovery Time	t _{rr}		62		ns	$I_F = -75 \text{ A}, V_{GS} = 0 \text{ V},$
Reverse Recovery Charge	Q _{rr}		65		nC	di/dt = 100 A/μs

Note: *1. Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

TEST CIRCUIT 2 SWITCHING TIME



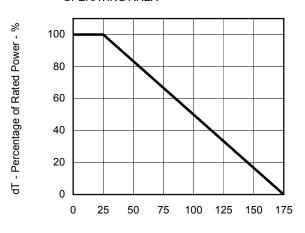


TEST CIRCUIT 3 GATE CHARGE

$$\begin{array}{c|c} \text{D.U.T.} & & \\ \text{Ig} = -2 \text{ mA} & & \\ \hline \\ \text{PG.} & & \\ \hline \\ \end{array} \begin{array}{c} \text{S} \text{ 50 } \Omega \\ \end{array} \begin{array}{c} \text{Vol} \\ \end{array}$$

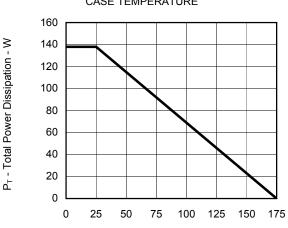
Typical Characteristics ($T_A = 25^{\circ}C$)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



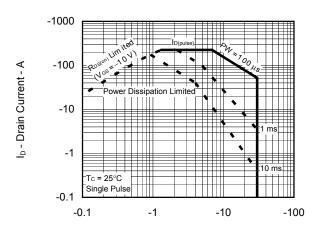
T_C - Case Temperature - °C

TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



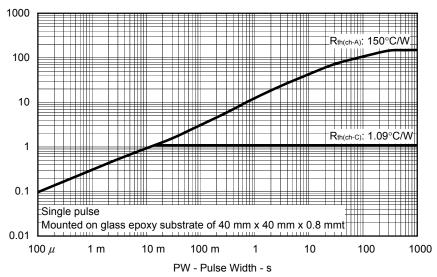
T_C - Case Temperature - °C

FORWARD BIAS SAFE OPERATING AREA



 $V_{\text{\scriptsize DS}}$ - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



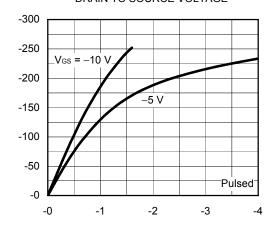


I_D - Drain Current - A

V_{GS(th)} - Gate to Source Threshold Voltage - V

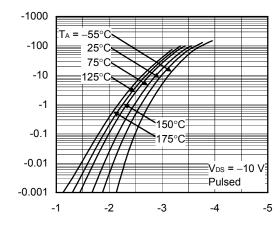
 $R_{\text{DS}(\text{on})}$ - Drain to Source On-state Resistance - $m\Omega$

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



 $V_{\text{\scriptsize DS}}$ - Drain to Source Voltage - V

FORWARD TRANSFER CHARACTERISTICS

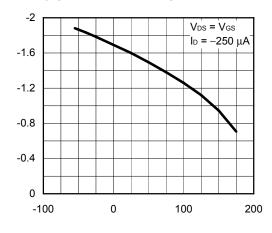


Ip - Drain Current - A

y_{fs} | - Forward Transfer Admittance - S

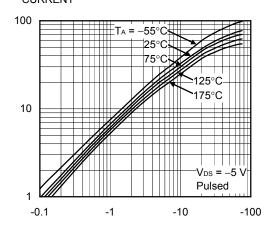
V_{GS} - Gate to Source Voltage - V

GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



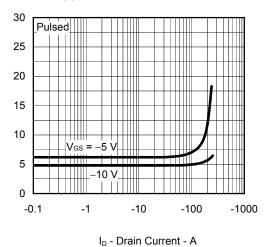
T_{ch} - Channel Temperature - °C

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

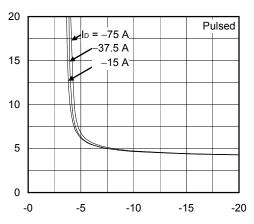


ID - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



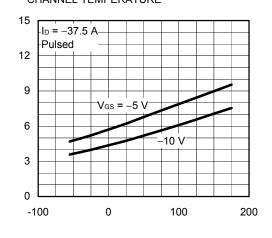
 V_{GS} - Gate to Source Voltage - V

 $R_{\text{DS}(\text{on})}$ - Drain to Source On-state Resistance - $m\Omega$

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

t_{d(on)}, t_r, t_{d(off)}, t_f - Switching Time - ns

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



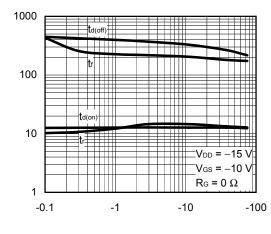
 T_{ch} - Channel Temperature - $^{\circ}C$

10000 La - 000 1000 1000 Coss Coss Crss VGS = 0 V f = 1 MHz -0.1 -1 -10 -100

V_{DS} - Drain to Source Voltage - V

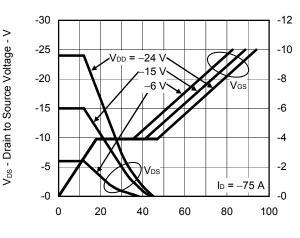
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

SWITCHING CHARACTERISTICS



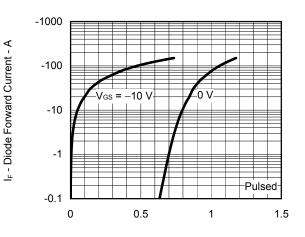
ID - Drain Current - A

DYNAMIC INPUT/OUTPUT CHARACTERISTICS



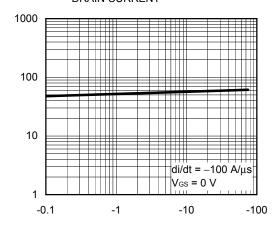
Q_G - Gate Charge - nC

SOURCE TO DRAIN DIODE FORWARD VOLTAGE



 $V_{\text{F(S-D)}}$ - Source to Drain Voltage - V

REVERSE RECOVERY TIME vs. DRAIN CURRENT

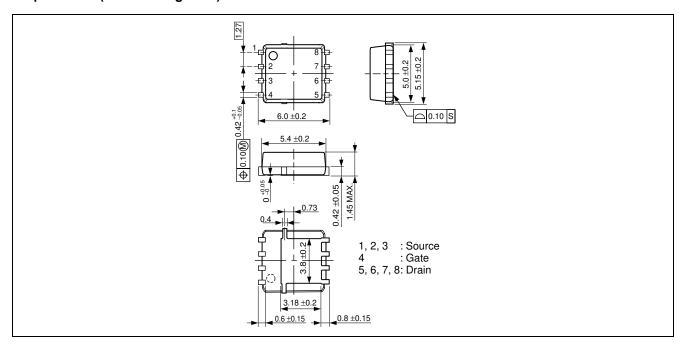


I_F - Drain Current - A

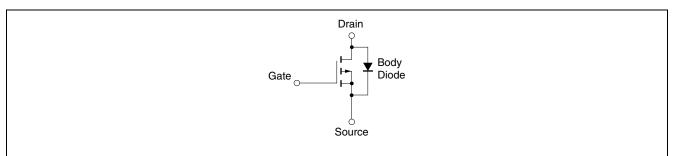
t_{rr} - Reverse Recovery Time - ns

Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



Equivalent Circuit



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

Revision History

NP75P03YDG Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Jul 01, 2010	-	First Edition Issued	
2.00	Mar 16, 2011	p.1	Repetitive Avalanche Current -> Single Avalanche Current	
			Repetitive Avalanche Energy -> Single Avalanche Energy	
			Modification of Note *3	

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